

Data Sheet

The SST12LP14 is a high-performance power amplifier IC based on the highlyreliable InGaP/GaAs HBT technology. Easily configured for high-power, high-efficiency applications with superb power-added efficiency, it typically provides 30 dB gain with 22% power added efficiency. The SST12LP14 has excellent linearity while meeting 802.11g spectrum mask at 23 dBm.It is ideal for the final stage power amplification in battery-powered 802.11g/b WLAN transmitter applications, and is offered in 16-contact VQFN package.

# Features

- High Gain:
  - Typically 30 dB gain across 2.4~2.5 GHz over temperature 0°C to +80°C
- High linear output power:
  - >26.5 dBm P1dB
  - Meets 802.11g OFDM ACPR requirement up to 23 dBm
     Added EVM ~4% up to 20 dBm for
  - 54 Mbps 802.11g signal
  - Meets 802.11b ACPR requirement up to 24 dBm
- High power-added efficiency/Low operating current for both 802.11g/b applications
  - ~22% @ P<sub>OUT</sub> = 22 dBm for 802.11g - ~26% @ P<sub>OUT</sub> = 23.5 dBm for 802.11b
- Built-in Ultra-low I<sub>BEF</sub> power-up/down control
  - I<sub>BFF</sub> <4 mA

#### Low idle current

– ~60 mA Ico

#### • High-speed power-up/down

- Turn on/off time (10%~90%) <100 ns
- Typical power-up/down delay with driver delay included <200 ns</li>
- High temperature stability
  - ~1 dB gain/power variation between 0°C to +80°C
  - ~1 dB detector variation over 0°C to +80°C
- Low shut-down current (< 0.1 μA)</li>
- On-chip power detection
- 25 dB dynamic range on-chip power detection
- Simple input/output matching
- Packages available
  - 16-contact VQFN (3mm x 3mm)
  - Non-Pb (lead-free) packages available

# Applications

- WLAN (IEEE 802.11g/b)
- Home RF
- Cordless phones
- 2.4 GHz ISM wireless equipment



Data Sheet

## **Product Description**

The SST12LP14 is a high-performance power amplifier IC based on the highly-reliable InGaP/GaAs HBT technology.

The SST12LP14 can be easily configured for high-power, high-efficiency applications with superb power-added efficiency while operating over the 2.4~2.5 GHz frequency band. It typically provides 30 dB gain with 22% power-added efficiency @  $P_{OUT} = 22$  dBm for 802.11g and 27% power-added efficiency @  $P_{OUT} = 24$  dBm for 802.11b.

The SST12LP14 has excellent linearity, typically <4% added EVM up to 20 dBm output power which is essential for 54 Mbps 802.11g operation while meeting 802.11g spectrum mask at 23 dBm. The SST12LP14 also has wide-range (>25 dB), temperature-stable (~1 dB over 80°C), single-ended/differential power detectors which lower users' cost on power control.

The power amplifier IC also features easy board-level usage along with high-speed power-up/ down control. Ultra-low reference current (total  $I_{REF} < 4$  mA) makes the SST12LP14 controllable by an on/off switching signal directly from the baseband chip. These features coupled with low operating current make the SST12LP14 ideal for the final stage power amplification in battery-powered 802.11g/b WLAN transmitter applications.

The SST12LP14 is offered in 16-contact VQFN package. See Figure 2 for pin assignments and Table 1 for pin descriptions.



Data Sheet

## **Functional Blocks**



Figure 1: Functional Block Diagram



Data Sheet

## **Pin Assignments**



Figure 2: Pin Assignments for 16-contact VQFN

#### **Pin Descriptions**

Symbol	Pin No.	Pin Name	Type <sup>1</sup>	Function
GND	0	Ground		The center pad should be connected to RF ground with several low inductance, low resistance vias.
NC	1	No Connection		Unconnected pins.
RFIN	2		I	RF input, DC decoupled
RFIN	3		I	RF input, DC decoupled
NC	4	No Connection		Unconnected pins.
VCCb	5	Power Supply	PWR	Supply voltage for bias circuit
VREF1	6		PWR	1st stage idle current control
VREF2	7		PWR	2nd stage idle current control
Det_ref	8		0	On-chip power detector reference
Det	9		0	On-chip power detector
RFOUT	10		0	RF output
RFOUT	11		0	RF output
VCC2	12	Power Supply	PWR	Power supply, 2nd stage
NC	13	No Connection		Unconnected pins.
NC	14	No Connection		Unconnected pins.
NC	15	No Connection		Unconnected pins.
VCC1	16	Power Supply	PWR	Power supply, 1st stage

#### Table 1: Pin Description

1. I=Input, O=Output



Data Sheet

## **Electrical Specifications**

The AC and DC specifications for the power amplifier interface signals. Refer to Table 3 for the DC voltage and current specifications. Refer to Figures 3 through 13 for the RF performance.

**Absolute Maximum Stress Ratings** (Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Supply Voltage at pins 5, 12, and 16 (V <sub>CC</sub> )	0.3V to +4.6V
Reference voltage to pin 6 (V <sub>REF1</sub> ) and pin 7 (V <sub>REF2</sub> )	0.3V to +3.6V
DC supply current (I <sub>CC</sub> )	500 mA
Operating Temperature (T <sub>A</sub> )	40°C to +85°C
Storage Temperature (T <sub>STG</sub> )	40°C to +120°C
Maximum Junction Temperature (T <sub>J</sub> )	+150°C
Surface Mount Solder Reflow Temperature: "with-Pb" units1: 24	0°C for 3 seconds
"non-Pb" units: 26	0°C for 3 seconds

1. Certain "with-Pb" package types are capable of 260°C for 3 seconds; please consult the factory for the latest information.

#### Table 2: Operating Range

Range	Ambient Temp	V <sub>DD</sub>
Industrial	-40°C to +85°C	3.3V

T2.1 75031

Symbol	Parameter	Min.	Тур	Max.	Unit	Test Conditions
V <sub>CC</sub>	Supply Voltage at pins 5, 12, 16	3.0	3.3	4.2	V	
I <sub>CC</sub>	Supply Current					
	for 802.11g, 24 dBm			290	mA	
	for 802.11g, 25 dBm			340	mA	
I <sub>CQ</sub>	Idle current for 802.11g to meet EVM @ 20.5 dBm		55		mA	
I <sub>OFF</sub>	Shut down current			0.1	μA	
V <sub>REG1</sub>	Reference Voltage for 1st Stage, with $120\Omega$ resistor	2.7	2.9	3.1	V	
V <sub>REG2</sub>	Reference Voltage for 2nd Stage, with $360\Omega$ resistor	2.7	2.9	3.1	V	
V <sub>REG1</sub>	Reference Voltage for 1st Stage, with $220\Omega$ resistor	2.9	3.1	3.3	V	
V <sub>REG2</sub>	Reference Voltage for 2nd Stage, with 590 $\Omega$ resistor	2.9	3.1	3.3	V	

#### Table 3: DC Electrical Characteristics

T3.0 75031



Data Sheet

Symbol	Parameter	Min.	Тур	Max.	Unit
F <sub>L-U</sub>	Frequency range	2400		2485	MHz
Pout	Output power				
	@ PIN = -7 dBm 11b signals	23			dBm
	@ PIN = -10 dBm 11g signals	20			dBm
G	Small signal gain	30	31	33	dB
G <sub>VAR1</sub>	Gain variation over band (2400~2485 MHz)			±0.5	dB
G <sub>VAR2</sub>	Gain ripple over channel (20 MHz)		0.2		dB
ACPR	Meet 11b spectrum mask	23			dBm
	Meet 11g OFDM 54 MBPS spectrum mask	22			dBm
Added EVM	@ 20 dBm output with 11g OFDM 54 MBPS signal		3		%
2f, 3f, 4f, 5f	Harmonics at 22 dBm, without trapping capacitors			-40	dBc
		•	•	•	T4.0 7503

#### Table 4: AC Electrical Characteristics for Configuration

©2011 Silicon Storage Technology, Inc.



Data Sheet

# **Typical Performance Characteristics**

### Test Conditions: $V_{CC} = 3.3V$ , $T_A = 25^{\circ}C$



Figure 3: S-Parameters







Data Sheet



Figure 5: In-band Gain Flatness



Data Sheet

## **Typical Performance Characteristics**

#### Test Conditions: F1 = 2.45 GHz, F2 = 2.451 GHz



#### Figure 6: P<sub>OUT</sub> vs P<sub>IN</sub>



#### Figure 7: IM3 vs POUT



Data Sheet













Data Sheet

## **Typical Performance Characteristics**

Test Conditions:  $V_{CC}$  = 3.3V,  $T_A$  = 25°C, F = 2.45 GHz, 54 Mbps 802.11g OFDM signal



Figure 11:802.11g Spectrum at 22/23 dBm, DC current 210/240 mA







Data Sheet



Figure 13:802.11b Spectrum at 24 dBm, DC current consumption 280 mA







Data Sheet

### **Product Ordering Information**



1. Environmental suffix "E" denotes non-Pb solder. SST non-Pb solder devices are "RoHS Compliant".

#### Valid combinations for SST12LP14

SST12LP14-QVC SST12LP14-QVCE

#### SST12LP14 Evaluation Kits

SST12LP14-QVC-K SST12LP14-QVCE-K

Note: Valid combinations are those products in mass production or will be in mass production. Consult your SST sales representative to confirm availability of valid combinations and to determine availability of new combinations.



Data Sheet

# **Packaging Diagrams**



SST Package Code: QVC



Data Sheet

#### Table 5: Revision History

Revision	Description		Date	
00	DS75031: SST conversion of data sheet GP1214		Jan 2005	
01	•	Updated document status from Preliminary Specification to Data Sheet	Apr 2008	
02	•	Updated "Contact Information" on page 12.	Feb 2009	
A	•	Applied new document format	Oct 2011	
	•	Released document under letter revision system		
	•	Updated Spec number from S71279 to DS75031		

ISBN:978-1-61341-699-0

© 2011 Silicon Storage Technology, Inc-a Microchip Technology Company. All rights reserved.

SST, Silicon Storage Technology, the SST logo, SuperFlash, MTP, and FlashFlex are registered trademarks of Silicon Storage Technology, Inc. MPF, SQI, Serial Quad I/O, and Z-Scale are trademarks of Silicon Storage Technology, Inc. All other trademarks and registered trademarks mentioned herein are the property of their respective owners.

Specifications are subject to change without notice. Refer to www.microchip.com for the most recent documentation. For the most current package drawings, please see the Packaging Specification located at http://www.microchip.com/packaging.

Memory sizes denote raw storage capacity; actual usable capacity may be less.

SST makes no warranty for the use of its products other than those expressly contained in the Standard Terms and Conditions of Sale.

For sales office locations and information, please see www.microchip.com.

#### Silicon Storage Technology, Inc. A Microchip Technology Company www.microchip.com



Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию.

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России, а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научноисследовательскими институтами России.

С нами вы становитесь еще успешнее!

#### Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург, Промышленная ул, дом № 19, литера Н, помещение 100-Н Офис 331